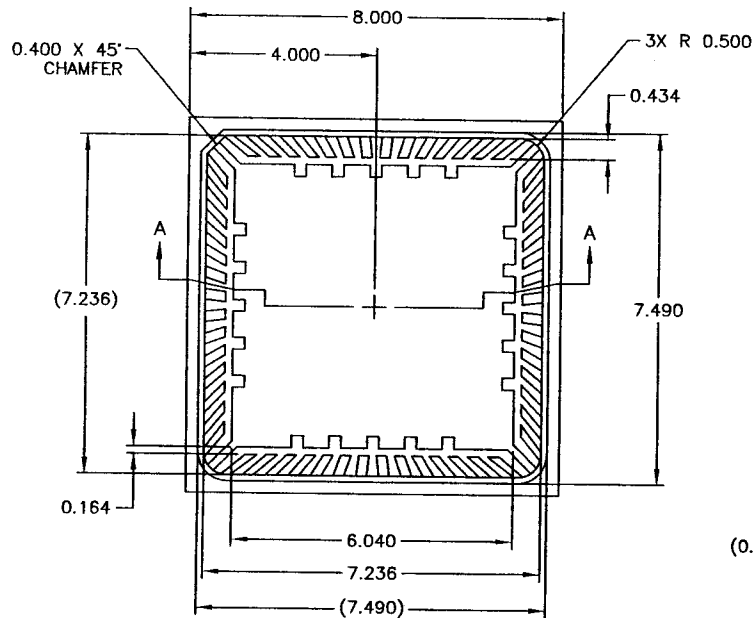
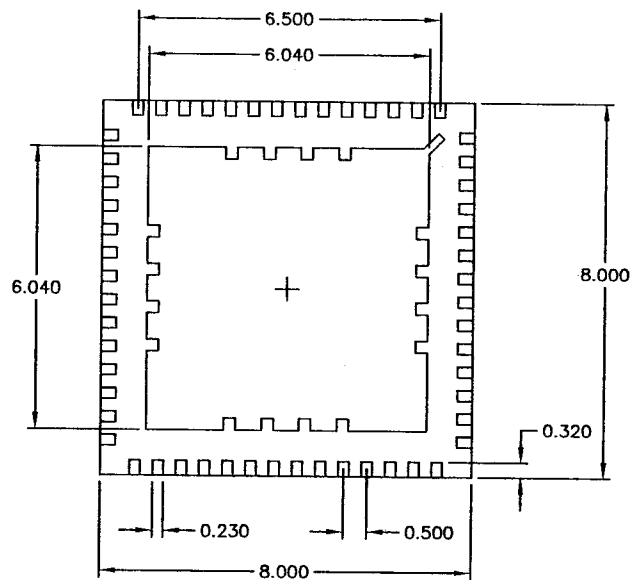
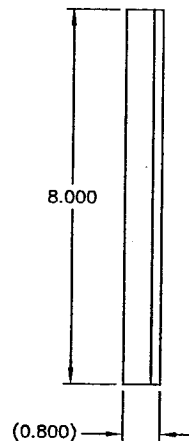


# SSM P/N QFN05601

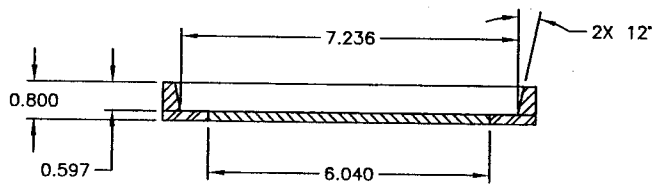
REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
		PRODUCTION RELEASE	



TOP VIEW



BOTTOM VIEW



SECTION A-A

NOTES:

1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
2. LEAD FRAME: COPPER, 194 FH.
3. LEAD FINISH: FULL GOLD PLATE.
4. LEAD FINISH: FULL GOLD PLATE.
5. FRAME THICKNESS: 0.2030 ± 0.0076.
6. DIE PAD: 6.040 X 6.040.
7. JEDEC OUTLINE: MO-220 (VLD-5).

	THIRD ANGLE PROJECTION	DRAWN BY	DATE
	UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE:	APP BY	DATE
X.XX ± 0.15	X.XXXX ± ---	CUSTOMER	
X.XXX ± 0.100	ANGLES: ± 1°		
DO NOT SCALE DRAWING			

DRAWN BY	DATE
APP BY	DATE
CUSTOMER	

56 Lead 8mm x 8mm

**QFN8X8-056 REV 3**

